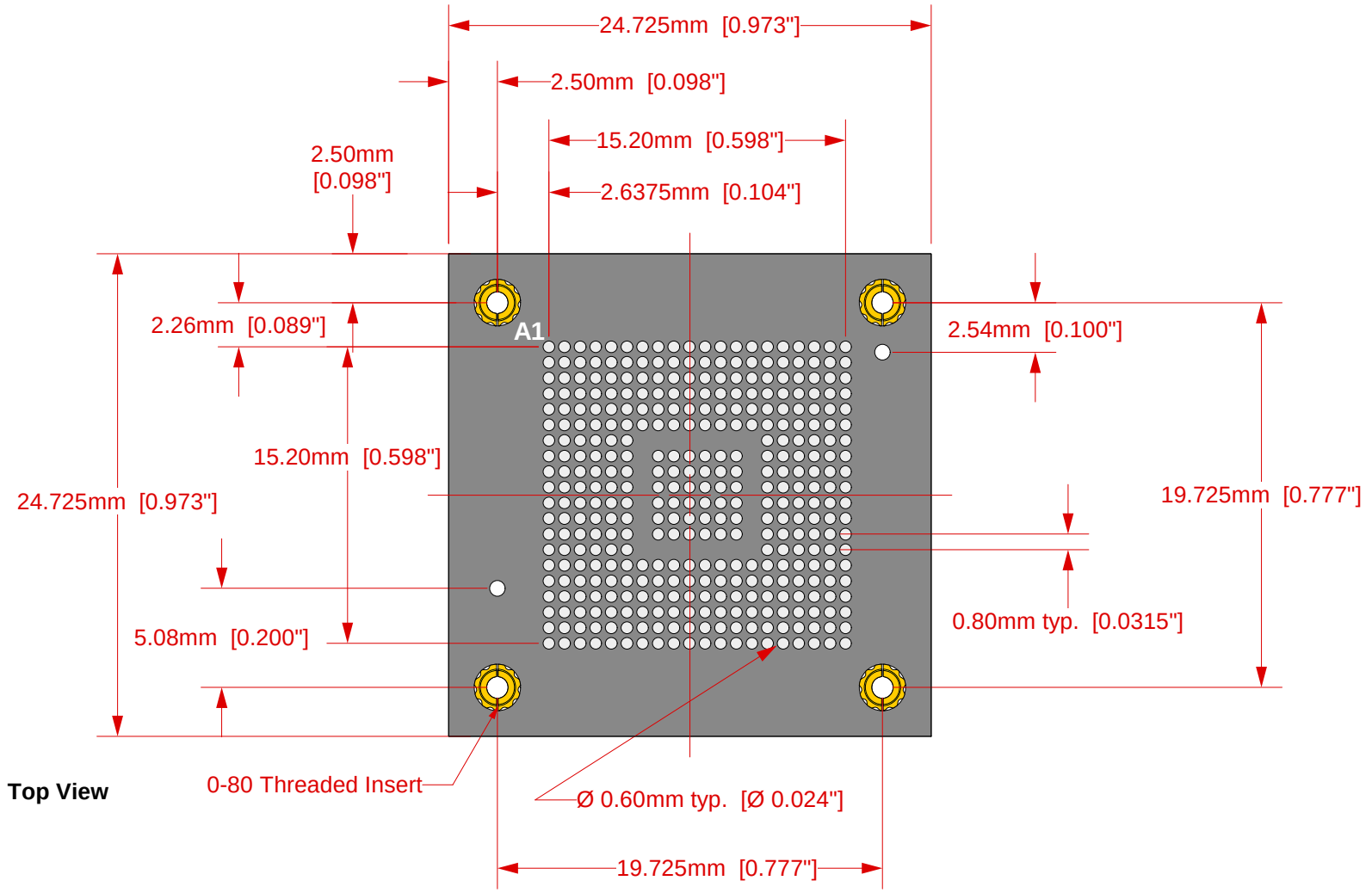
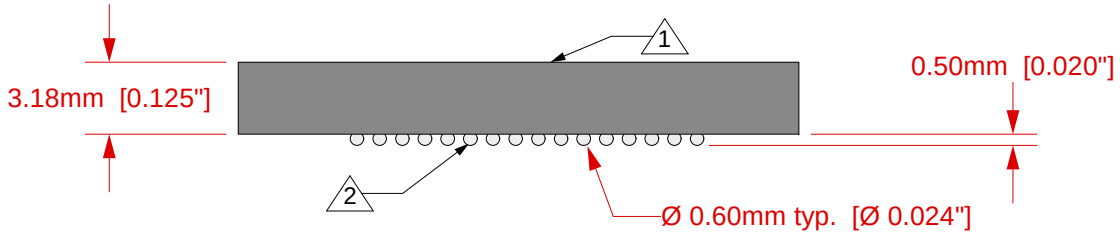


Top View



Side View

1 Substrate: 3.18mm ±0.025mm [0.125" ±0.001"] per IPC 4101/21, Gold surface finish.

2 Solder ball: SAC305 alloy

Description: BGA Surface Mount Adaptor
372 position surface mount land pattern to solder balls. To be used with GHz sockets.

RoHS

Tolerances: diameters ±0.03mm [±0.001"], PCB perimeters ±0.13mm [±0.005"], PCB thicknesses ±0.18mm [±0.007"], pitches (from true position) ±0.08mm [±0.003"], all other tolerances ±0.13mm [±0.005"] unless stated otherwise. Materials and specifications are subject to change without notice.

SF-BGA372C-B-05 Drawing	Status: Released	Scale: 3:1	Rev: A
© 2010 IRONWOOD ELECTRONICS, INC. 11351 Rupp Drive, Suite 400, Burnsville, MN 55337 Tele: (952) 229-8200 www.ironwoodelectronics.com	Drawing: E Smolentseva		Date: 1/21/10
	File: SF-BGA372C-B-05 Dwg		Modified: